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- (71) Applicant: **APPLIED MATERIALS, INC.** [US/US];  
3050 Bowers Avenue, Santa Clara, California 95054 (US).
- (72) Inventors: **BAJAJ, Rajeev**; 43651 Skye Road, Fremont, California 94539 (US). **REDFIELD, Daniel**; 1445 Kelly Park Circle, Morgan Hill, California 95037 (US). **ORILALL, Mahendra C.**; 1700 Civic Center Dr. #602, Santa Clara, California 95050 (US). **FU, Boyi**; 1164 McKay Dr., San Jose, California 95131 (US). **KHANNA, Aniruddh Jagdish**; 2472 Autumnvale Drive, San Jose, California 95131 (US). **FUNG, Jason G.**; 355 North Wolfe Road, Apt. 332, Sunnyvale, California 94085 (US). **CORNEJO, Mario**; 5782 Orchard Park Drive, San Jose, California 95123 (US). **CHOCKALINGAM, Ashwin**; 320 Crescent Village Circle, San Jose, California 95134 (US). **YAMAMURA, Mayu Felicia**; 593 Cedar St., San Carlos,

California 94070-2131 (US). **KAKIREDDY, Raghava**; 1620 Hope Dr., Apt. # 526, Santa Clara, California 95054 (US). **KUMAR, Ashavani**; 1235 Wildwood Ave., Apt. 23, Sunnyvale, California 94089 (US). **HARIHARAN, Venkatachalam**; 1921 Cape Horn Dr., San Jose, California 95133 (US). **MENK, Gregory E.**; 1833 Greenwood Road, Pleasanton, California 94566 (US). **REDEKER, Fred C.**; 1801 Sioux Drive, Fremont, California 94536 (US). **PATIBANDLA, Nag B.**; 3951 Vierra, Pleasanton, California 94566 (US). **NG, Hou Tee**; 4068 Keith Drive, Campbell, California 95008 (US). **DAVENPORT, Rob**; 14650 Eastview Drive, Los Gatos, California 95032 (US). **SINHA, Amritanshu**; 880 E. Fremont Ave., Apt. 107, Sunnyvale, California 94087 (US).

(74) Agents: **PATTERSON, B. Todd** et al.; Patterson & Sheridan, L.L.P., 24 Greenway Plaza, Suite 1600, Houston, Texas 77046 (US).

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(54) Title: POLISHING PADS PRODUCED BY AN ADDITIVE MANUFACTURING PROCESS

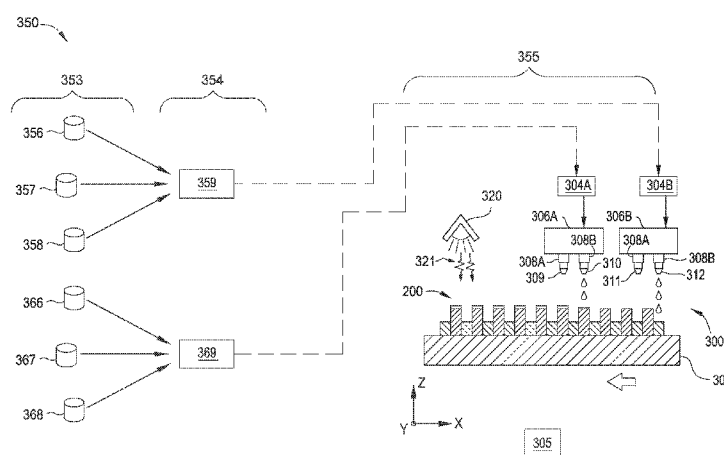


FIG. 3A

(57) Abstract: Embodiments of the present disclosure relate to advanced polishing pads with tunable chemical, material and structural properties, and new methods of manufacturing the same. According to one or more embodiments of the disclosure, it has been discovered that a polishing pad with improved properties may be produced by an additive manufacturing process, such as a three-dimensional (3D) printing process. Embodiments of the present disclosure thus may provide an advanced polishing pad that has discrete features and geometries, formed from at least two different materials that include functional polymers, functional oligomers, reactive diluents, and curing agents. For example, the advanced polishing pad may be formed from a plurality of polymeric layers, by the automated sequential deposition of at least one resin precursor composition followed by at least one curing step, wherein each layer may represent at least one polymer composition, and/or regions of different compositions.



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